

CLAIMS

1. A thermal printhead comprising: an insulating substrate; a common electrode formed on the insulating substrate and including a plurality of comb teeth; a plurality of individual electrodes formed on the insulating substrate; and a resistor layer formed on the insulating substrate and electrically connected to the comb teeth and the individual electrodes;
wherein the resistor layer comprises a thin film, whereas
10 the common electrode and the individual electrodes comprise a thick film.
2. The thermal printhead according to claim 1, wherein the resistor layer has a film thickness of 0.05 to 0.2 μm , whereas
15 the common electrode and the individual electrodes have a film thickness of 0.3 to 1.0 μm .
3. The thermal printhead according to claim 1, wherein the resistor layer is in a form of an elongated strip and partially
20 covers the comb teeth of the common electrode and the individual electrodes alternately.
4. The thermal printhead according to claim 1, wherein the comb teeth and the individual electrodes have respective front ends
25 facing and spaced from each other; and
wherein the resistor layer is divided into a plurality of electrically-separated resistor portions correspondingly

to the comb teeth and the individual electrodes, each of the resistor portions being positioned between the front end of one of the comb teeth and the front end of the corresponding one of the individual electrodes.

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5. The thermal printhead according to claim 1, wherein the resistor layer, the common electrode and the individual electrodes are covered by a protective layer.

10 6. A method for manufacturing a thermal printhead, comprising the steps of:

forming a common electrode and a plurality of individual electrodes on an insulating substrate, the common electrode including a plurality of comb teeth; and

15 forming a resistor layer for electrical connection to the common electrode and the individual electrodes;

wherein the step of forming the common electrode and the plurality of individual electrodes comprises forming a thick film of conductive material; and

20 wherein the step of forming the resistor layer comprises forming a thin film of resistive material.

7. The thermal printhead manufacturing method according to claim 6, wherein the step of forming the common electrode and the plurality of individual electrodes is so performed that the 25 thick film has a film thickness of 0.3 to 1.0 μm .

- 8 . The thermal printhead manufacturing method according to claim 7 , wherein the step of forming the resistor layer is so performed that the thin film has a film thickness of 0.05 to 0.2 μ m.
- 5 9 . The thermal printhead manufacturing method according to claim 7 , wherein the step of forming the common electrode and the plurality of individual electrodes comprises thick-film printing of the conductive material.
- 10 10. The thermal printhead manufacturing method according to claim 7 , wherein the step of forming the resistor layer is performed by a technique selected from the group consisting of sputtering, vacuum evaporation, CVD and plating.